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(54) Title: CONDUCTIVE CONNECTION SHEET, METHOD FOR CONNECTING TERMINALS, METHOD FOR FORMING CONNECTION TERMINAL, SEMICONDUCTOR DEVICE, AND ELECTRONIC DEVICE

(54) 発明の名称: 導電接続シート、端子間の接続方法、接続端子の形成方法、半導体装置および電子機器

[図2]

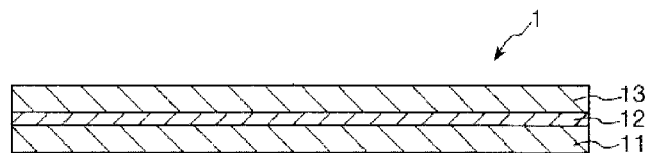


FIG. 2

(57) Abstract: Disclosed is a conductive connection sheet (1) comprised of a laminated body provided with resin composition layers (11, 13) and a metal layer (12). The resin composition layers (11, 13) satisfy the following Requirement A. When the conductive connection sheet (1) having the aforementioned structure is applied to the forming of a connection portion for electrically connecting terminals to each other, heated and melted metal material can be selectively aggregated between the terminals, to form a connection portion, and a sealing layer composed of a resin component can be formed around the connection portion. Consequently, the periphery of the connection portion can be covered by a resin component and, thus, the connection portion is affixed. Furthermore, the insulation performance between the adjacent terminals is ensured by the sealing layer and, accordingly, leakage current can be reliably prevented from occurring between the adjacent terminals. Requirement A: While at least a part of each metal ball composed of a metal material having a low melting point is disposed within the resin composition layers (11, 13), the metal ball is heated to a temperature not less than the melting temperature of the metal ball in accordance with the soldering resin flux test method prescribed in JIS Z 3197. After that, the wet extension of the metal ball is measured, and the wet extension is 37% or more.

(57) 要約:

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